

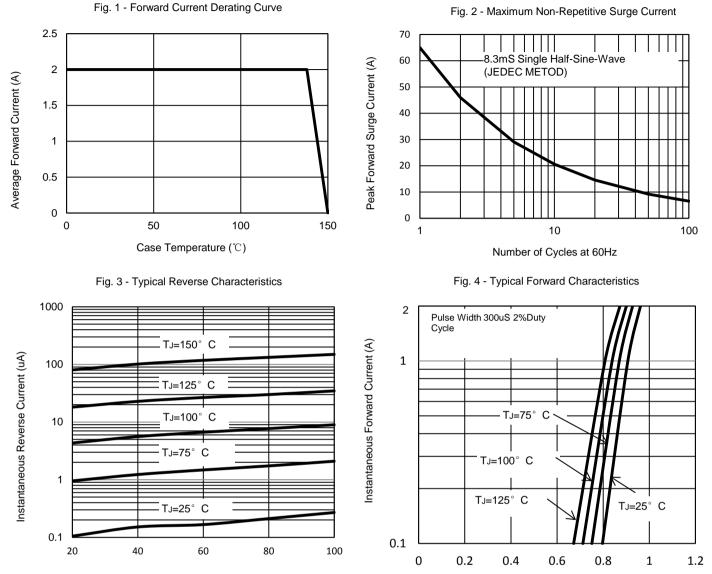
D2KB05 THRU D2KB10

Features Glass passivated chip Low forward voltage drop Ideal for printed circuit board 		D3K						Reverse Voltage - 50 to 1000 Volts Forward Current - 2.0 Amperes							
•				/	17				RoHS						
 High surge current capability Meet UL flammability classification 94V-0 			.057 (1.4 <u>R2</u>		(14.1) (13.5)			.130 (3.3) .114 (2.9) .110 (2.8) .094 (2.4)	OMPLIANT						
 Mechanical Data Polarity: Symbol marked on body Mounting position: Any Note: Products with logo or boost or are made by HY Electronic (Cayman) Limited. Applications General purpose use in AC/DC bridge full wave rectification for SMPS, lighting ballaster, adapter, etc. 	۱,			(4.11)(2	.04	$\begin{array}{c} \hline (0,1) \\ \hline (0,1) \hline \hline (0,1) \hline$									
Maximum Ratings and Electrical Character Rating at 25°C ambient temperature unless otherwise specific Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.			uonugo					illimeters)	, 						
Characteristics	Symbol	D2KB05	D2KB1	D2KB2	D2KB4	D2KB6	D2KB8	D2KB10	UNIT						
Maximum Repetitive Peak Reverse Voltage	Vrrm	50	100	200	400	600	800	1000	V						
Maximum RMS Voltage	Vrms	35	70	140	280	420	560	700	V						
Maximum DC Blocking Voltage	VDC	50	100	200	400	600	800	1000	V						
Maximum Average Forward Rectified Current @Tc=138°C	I(AV)	2						А							
Peak Forward Surge Current, 8.3mS Single Half Sine-Wave, Superimposed on Rated Load (JEDEC Method)	IFSM	65							A						
² t Rating for Fusing (t<8.3mS)	l ² t	17.5						A ² s							
Peak Forward Voltage per Diode at 2.0A DC	VF	1.05						V							
Typical Thermal Resistance to Ambient (without heatsink)	Reja	55						°C/W							
Typical Thermal Resistance to case (with heatsink (Note2))	Rejc	1.5						°C/W							
Typical Thermal Resistance to lead (without heatsink)	Rejl	15						°C/W							
Maximum DC Reverse Current at Rated @Tj=25°C DC Blocking Voltage per Diode @Tj=125°C	IR	5 500							μA						
DO DIOGRING VOILAGE PER DIOUE WIJ=120 C															
Operating Junction Temperature Range	TJ			-	55 to +15	0			°C						

Notes: 1. Device mounted on 50mm*50mm*1.6mm Cu plate heatsink.

2. The typical data above is for reference only





Percent of Rated Peak Reverse Voltage (%)

Instantaneous Forward Voltage (V)

The curve above is for reference only.

Disclaimer

ALL specifications and data are subject to be changed without notice to improve reliability function or design or other reasons.

HY makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the cotinuing production of any product. To the maximum extent permitted by applicable law, HY disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on HY's knowledge of typical requirements that are often placed on HY products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application.Parameters provided in datasheets and specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify HY's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, HY products are not designed for use in medical, life-saving, or life-sustaining applications or for any other applications in which the failure of the HY product could result in personal injury or death. Customers using or selling HY products not expressly indicated for use in such applications do so at their own risk.Please contact authorized HY personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of HY. Product names and markings noted herein may be trademarks of their respective owners.